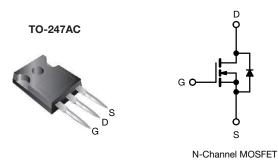
SiHG080N60E

Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	650		
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.070	
Q _g max. (nC)	6	3	
Q _{gs} (nC)	19		
Q _{gd} (nC)	1	0	
Configuration	Single		

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free and halogen-free	SIHG080N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V _{DS}	600	V
Gate-source voltage			V _{GS}	± 30	v
Continuous drain surrant $(T_{1} - 150 ^{\circ}\text{C})$	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	1-	35	
Continuous drain current ($T_J = 150 \ ^{\circ}C$)	V _{GS} at 10 V	T _C = 100 °C	Ι _D	22	А
Pulsed drain current ^a			I _{DM}	96	
Linear derating factor				1.8	W/°C
Single pulse avalanche energy ^b			E _{AS}	226	mJ
Maximum power dissipation			PD	227	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope T _J = 125 °C		T _J = 125 °C		100	
Reverse diode dv/dt ^d			dv/dt	10	V/ns
Soldering recommendations (peak temperature) ^c	For	10 s		260	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

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COMPLIANT

HALOGEN

FREE



THERMAL RESISTANCE RAT	INGS							
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum junction-to-ambient	R _{thJA}	-		40			°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-		0.55			0/10	
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$, u	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static						-		
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 μΑ	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 2	250 µA	3.0	-	5.0	V
		\	$V_{\rm GS} = \pm 20$	V	-	-	± 100	nA
Gate-source leakage	I _{GSS}	\ \	V _{GS} = ± 30	V	-	-	± 1	μA
Zara acta valtaga duain avurant		V _{DS} =	600 V, V _G	_S = 0 V	-	-	1	
Zero gate voltage drain current	IDSS	V _{DS} = 480 V	, V _{GS} = 0 V	∕, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	١	_D = 17 A	-	0.070	0.080	Ω
Forward transconductance a	9 _{fs}	V _{DS} :	= 20 V, I _D =	= 17 A	-	4.6	-	S
Dynamic						•	•	
Input capacitance	C _{iss}		$V_{GS} = 0 V$		-	2557	-	
Output capacitance	C _{oss}	$V_{DS} = 100 V,$ f = 1 MHz		-	105	-	-	
Reverse transfer capacitance	C _{rss}			-	6	-		
Effective output capacitance, energy related ^a	C _{o(er)}		(1. 400.)/		-	79	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}	$V_{\rm DS} = 0$ V	/ to 480 V,	$V_{GS} = 0 V$	-	499	-	
Total gate charge	Qg				-	42	63	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	I _D = 17	A, V _{DS} = 480 V	-	19	-	nC
Gate-drain charge	Q _{gd}				-	10	-	
Turn-on delay time	t _{d(on)}				-	31	62	
Rise time	t _r	V _{DD} =	: 480 V, I _D :	= 17 A,	-	96	144	
Turn-off delay time	t _{d(off)}	V _{GS} =	= 10 V, R _g =	= 9.1 Ω	-	37	74	ns
Fall time	t _f				-	31	62	
Gate input resistance	R _g	f = 1	MHz, oper	n drain	0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristi	cs							
Continuous source-drain diode current	۱ _S	MOSFET sym showing the	bol		-	-	35	
Pulsed diode forward current	I _{SM}	integral revers p - n junction			-	-	96	A
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 17 A	, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}				- 1	441	882	ns
Reverse recovery charge	Q _{rr}		5° C, $I_{F} = I_{S}$		-	5.2	10.4	μC
Reverse recovery current	I _{RRM}	ai/at =	80 A/µs, V	R = 23 V	-	21	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

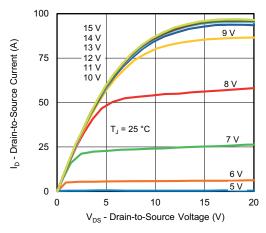


Fig. 1 - Typical Output Characteristics

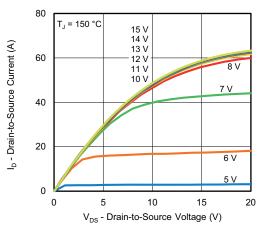


Fig. 2 - Typical Output Characteristics

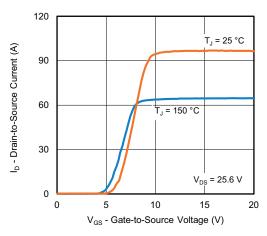


Fig. 3 - Typical Transfer Characteristics

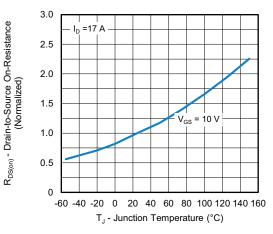


Fig. 4 - Normalized On-Resistance vs. Temperature

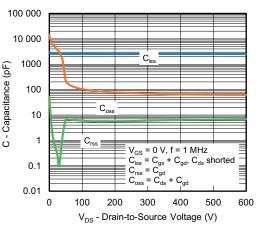


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

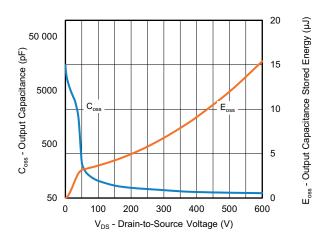


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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SiHG080N60E

Vishay Siliconix

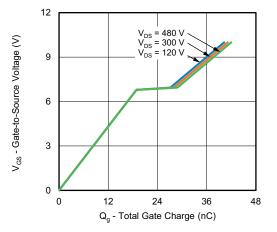


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

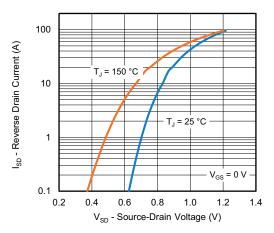


Fig. 8 - Typical Source-Drain Diode Forward Voltage

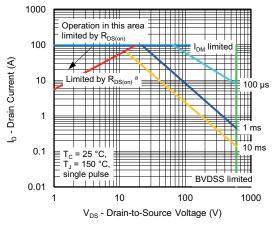


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

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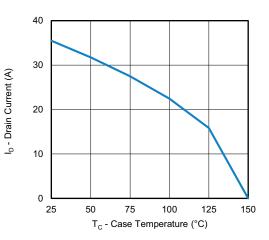


Fig. 10 - Maximum Drain Current vs. Case Temperature

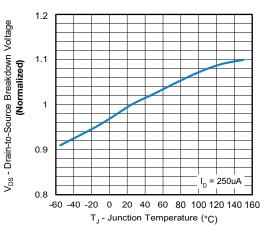
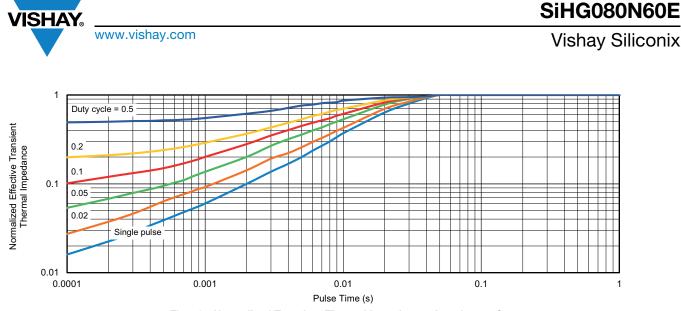


Fig. 11 - Temperature vs. Drain-to-Source Voltage





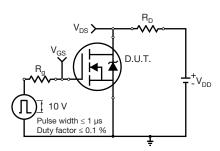


Fig. 13 - Switching Time Test Circuit

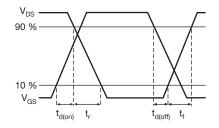


Fig. 14 - Switching Time Waveforms

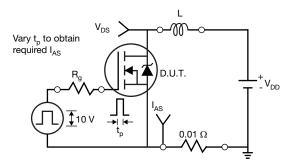


Fig. 15 - Unclamped Inductive Test Circuit

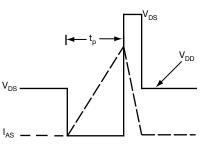


Fig. 16 - Unclamped Inductive Waveforms

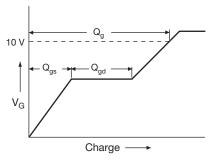


Fig. 17 - Basic Gate Charge Waveform

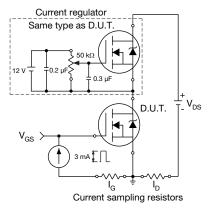


Fig. 18 - Gate Charge Test Circuit

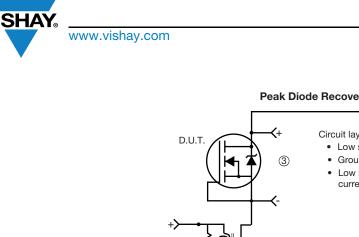
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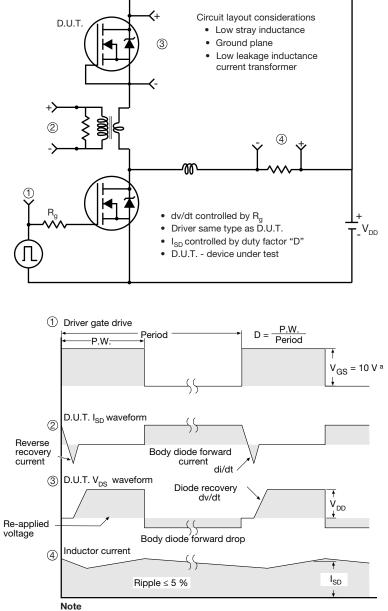
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Peak Diode Recovery dv/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel

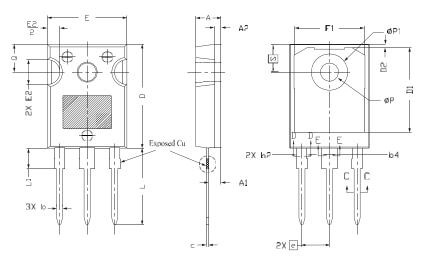
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TO-247AC (High Voltage)

VERSION 1: FACILITY CODE = 9





	М	ILLIMETERS		
DIM.	MIN.	NOM.	MAX.	NOTES
А	4.83	5.02	5.21	
A1	2.29	2.41	2.55	
A2	1.17	1.27	1.37	
b	1.12	1.20	1.33	
b1	1.12	1.20	1.28	
b2	1.91	2.00	2.39	6
b3	1.91	2.00	2.34	
b4	2.87	3.00	3.22	6, 8
b5	2.87	3.00	3.18	
С	0.40	0.50	0.60	6
c1	0.40	0.50	0.56	
D	20.40	20.55	20.70	4

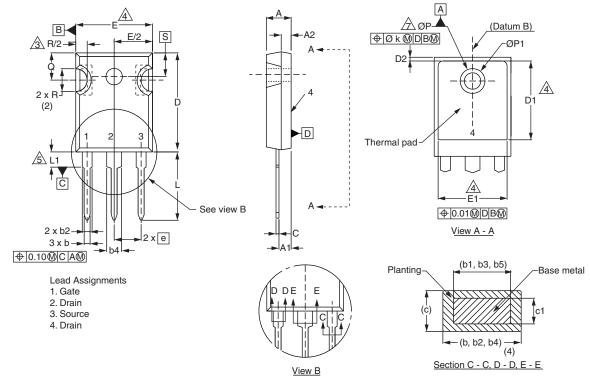
		MILLIMETER	S	
DIM.	MIN.	NOM.	MAX.	NOTES
D1	16.46	16.76	17.06	5
D2	0.56	0.66	0.76	
E	15.50	15.70	15.87	4
E1	13.46	14.02	14.16	5
E2	4.52	4.91	5.49	3
е		5.46 BSC		
L	14.90	15.15	15.40	
L1	3.96	4.06	4.16	6
ØР	3.56	3.61	3.65	7
Ø P1		7.19 ref.		
Q	5.31	5.50	5.69	
S		5.51 BSC		

Notes

- ⁽¹⁾ Package reference: JEDEC[®] TO247, variation AC
- (2) All dimensions are in mm
- ⁽³⁾ Slot required, notch may be rounded
- ⁽⁴⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm per side. These dimensions are measured at the outermost extremes of the plastic body
- ⁽⁵⁾ Thermal pad contour optional with dimensions D1 and E1
- (6) Lead finish uncontrolled in L1
- (7) Ø P to have a maximum draft angle of 1.5° to the top of the part with a maximum hole diameter of 3.91 mm
- (8) Dimension b2 and b4 does not include dambar protrusion. Allowable dambar protrusion shall be 0.1 mm total in excess of b2 and b4 dimension at maximum material condition



VERSION 2: FACILITY CODE = Y



	MILLIN	IETERS	
DIM.	MIN.	MAX.	NOTES
A	4.58	5.31	
A1	2.21	2.59	
A2	1.17	2.49	
b	0.99	1.40	
b1	0.99	1.35	
b2	1.53	2.39	
b3	1.65	2.37	
b4	2.42	3.43	
b5	2.59	3.38	
с	0.38	0.86	
c1	0.38	0.76	
D	19.71	20.82	
D1	13.08	-	

	MILLIN	IETERS	
DIM.	MIN.	MAX.	NOTES
D2	0.51	1.30	
E	15.29	15.87	
E1	13.72	-	
е	5.46	BSC	
Øk	0.2	254	
L	14.20	16.25	
L1	3.71	4.29	
ØР	3.51	3.66	
Ø P1	-	7.39	
Q	5.31	5.69	
R	4.52	5.49	
S	5.51	BSC	

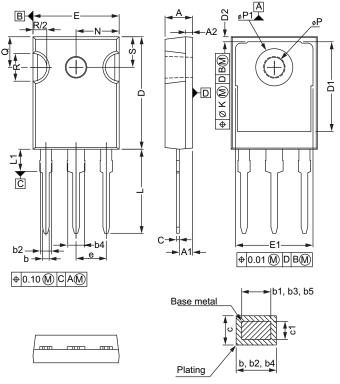
Notes

- ⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994
- ⁽²⁾ Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- ⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1
- ⁽⁵⁾ Lead finish uncontrolled in L1
- ⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- ⁽⁷⁾ Outline conforms to JEDEC outline TO-247 with exception of dimension c

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VERSION 3: FACILITY CODE = N



	MILLIN	IETERS		MILLIN	IETERS
DIM.	MIN.	MAX.	DIM.	MIN.	MAX
А	4.65	5.31	D2	0.51	1.35
A1	2.21	2.59	E	15.29	15.87
A2	1.17	1.37	E1	13.46	-
b	0.99	1.40	е	5.46	BSC
b1	0.99	1.35	k	0.:	254
b2	1.65	2.39	L	14.20	16.10
b3	1.65	2.34	L1	3.71	4.29
b4	2.59	3.43	N	7.62	BSC
b5	2.59	3.38	Р	3.56	3.66
С	0.38	0.89	P1	-	7.39
c1	0.38	0.84	Q	5.31	5.69
D	19.71	20.70	R	4.52	5.49
D1	13.08	-	S	5.51	BSC

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994

⁽²⁾ Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1

⁽⁵⁾ Lead finish uncontrolled in L1

⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")



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